

L Number	Hits	Search Text	DB	Time stamp
1	139336	second near3 (electrode or anode or cathode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:04
2	30857	(second near3 (electrode or anode or cathode)) and (second near3 (bias or voltage or potential))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:09
3	5419	((second near3 (electrode or anode or cathode)) and (second near3 (bias or voltage or potential))) and (alternat\$5 near5 (bias or voltage or potential))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:05
4	530	((((second near3 (electrode or anode or cathode)) and (second near3 (bias or voltage or potential))) and (alternat\$5 near5 (bias or voltage or potential))) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:06
5	186	(((((second near3 (electrode or anode or cathode)) and (second near3 (bias or voltage or potential))) and (alternat\$5 near5 (bias or voltage or potential))) and pad) and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:08
6	17900	(second near3 (bias or voltage or potential)) same (second near3 (electrode or anode or cathode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:10
7	97	(((((second near3 (electrode or anode or cathode)) and (second near3 (bias or voltage or potential))) and (alternat\$5 near5 (bias or voltage or potential))) and pad) and (copper or cu)) and ((second near3 (bias or voltage or potential)) same (second near3 (electrode or anode or cathode)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:31
8	23152	(electrode or anode or cathode) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8 or electroly\$8 or electrochem\$8) near5 (voltage or bias or potential)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:38
9	1283	(electrode or anode or cathode) near5 (etch\$8 or electroetch\$8 or polish\$8 or electropolish\$8) near5 (voltage or bias or potential)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:35
10	315	((electrode or anode or cathode) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8 or electroly\$8 or electrochem\$8) near5 (voltage or bias or potential)) and ((electrode or anode or cathode) near5 (etch\$8 or electroetch\$8 or polish\$8 or electropolish\$8) near5 (voltage or bias or potential))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:35
11	52	((((electrode or anode or cathode) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8 or electroly\$8 or electrochem\$8) near5 (voltage or bias or potential)) and ((electrode or anode or cathode) near5 (etch\$8 or electroetch\$8 or polish\$8 or electropolish\$8) near5 (voltage or bias or potential))) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:35
12	25501	(second\$5 near5 (electrode or anode or cathode)) near35 (second\$5 near5 (voltage or bias or potential))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:39

13	8	(((((electrode or anode or cathode) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8 or electroly\$8 or electrochem\$8) near5 (voltage or bias or potential))) and ((electrode or anode or cathode) near5 (etch\$8 or electroetch\$8 or polish\$8 or electropolish\$8) near5 (voltage or bias or potential)))) and pad) and ((second\$5 near5 (electrode or anode or cathode)) near35 (second\$5 near5 (voltage or bias or potential))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:43
14	28257	(substrate or workpiece or article or part or board or wafer) near5 (second\$5 near5 (electrode or cathode or anode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:46
15	28257	(substrate or workpiece or article or part or board or wafer) near5 (second\$5 near5 (electrode or cathode or anode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:47
16	2835	((substrate or workpiece or article or part or board or wafer) near5 (second\$5 near5 (electrode or cathode or anode))) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:47
17	564	((substrate or workpiece or article or part or board or wafer) near5 (second\$5 near5 (electrode or cathode or anode))) and pad) and (electroplat\$8 or electroly\$8 or electrochem\$8 or electrodeposit\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:47
18	397	(((((substrate or workpiece or article or part or board or wafer) near5 (second\$5 near5 (electrode or cathode or anode))) and pad) and (electroplat\$8 or electroly\$8 or electrochem\$8 or electrodeposit\$8)) and (etch\$8 or electroetch\$8 or polish\$8 or electropolish\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:48
19	91	(((((substrate or workpiece or article or part or board or wafer) near5 (second\$5 near5 (electrode or cathode or anode))) and pad) and (electroplat\$8 or electroly\$8 or electrochem\$8 or electrodeposit\$8)) and (etch\$8 or electroetch\$8 or polish\$8 or electropolish\$8)) and (second\$5 near3 (voltage or bias or potential))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:52
20	5235	(first or primary or initial) near5 (voltage or bias or potential) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:54
21	438	(second\$5 or final) near5 (voltage or bias or potential) near5 (etch\$5 or electroetch\$5 or polish\$5 or electropolish\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:55
22	15586	((first or primary or initial) near5 (voltage or bias or potential) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8)) nad ((second\$5 or final) near5 (voltage or bias or potential) near5 (etch\$5 or electroetch\$5 or polish\$5 or electropolish\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:56

23	17	((first or primary or initial) near5 (voltage or bias or potential) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8)) and ((second\$5 or final) near5 (voltage or bias or potential) near5 (etch\$5 or electroetch\$5 or polish\$5 or electropolish\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:56
24	5	((first or primary or initial) near5 (voltage or bias or potential) near5 (plat\$8 or deposit\$8 or electroplat\$8 or electrodeposit\$8)) and ((second\$5 or final) near5 (voltage or bias or potential) near5 (etch\$5 or electroetch\$5 or polish\$5 or electropolish\$5))) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:56

L Number	Hits	Search Text	DB	Time stamp
1	545	(anodes or cathodes or electrodes) same (plating or depositing or electorplating or electrodepositing) same (voltages or biases or potentials)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 17:32
3	71	((anodes or cathodes or electrodes) same (plating or depositing or electorplating or electrodepositing) same (voltages or biases or potentials)) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 17:32